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FDG6331L

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FAIRCHILD

SEMICONDUCTOR TM

FDG6331L Integrated Load Switch

General Description

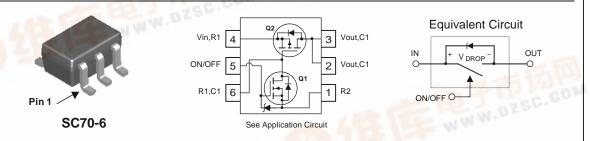
This device is particularly suited for compact power management in portable electronic equipment where 2.5V to 8V input and 0.8A output current capability are needed. This load switch integrates a small N-Channel power MOSFET (Q1) that drives a large P-Channel power MOSFET (Q2) in one tiny SC70-6 package.

Applications

- Power management
- Load switch

Features

- $\label{eq:rescaled_rescale$
- Control MOSFET (Q1) includes Zener protection for ESD ruggedness (>6KV Human body model)
- High performance trench technology for extremely low R_{DS(ON)}
- Compact industry standard SC70-6 surface mount package



Absolute Maximum Ratings T_A=25°C unless otherwise noted

Symbol	Parameter Gate-Source Voltage (Q2)		Ratings	Units	
V _{IN}			± 8	V	
V _{ON/OFF}	Gate-Source Voltage (Q1)		-0.5 to 8	V	
ILoad	Load Current – Continuous	(Note 2)	-0.8	А	
	– Pulsed	(Note 2)	-2.4		
PD	Maximum Power Dissipation	(Note 1)	0.3	W	
T_J, T_{STG}	Operating and Storage Junction Temperature Range		-55 to +150	°C	

Thermal Characteristics R_{eJA} Thermal Resistance, Junction-to-Ambient (Note 1a) 415

Package Marking and Ordering information					
Device Marking	Device	Reel Size	Tape width	Quantity	
.31	FDG6331L	7"	8mm	3000 units	



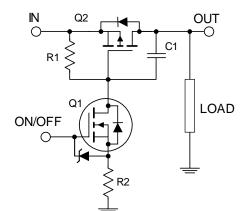
°C/W

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Char	acteristics					
BVIN	Vin Breakdown Voltage	$V_{ON/OFF} = 0 V, I_D = -250 \mu A$	8			V
I _{Load}	Zero Gate Voltage Drain Current	$V_{IN} = -6.4 \text{ V}, V_{ON/OFF} = 0 \text{ V}$			-1	μA
I _{FL}	Leakage Current, Forward	$V_{ON/OFF} = 0 V, V_{IN} = 8 V$			100	nA
I _{RL}	Leakage Current, Reverse	$V_{ON/OFF} = 0 V, V_{IN} = -8 V$			-100	nA
On Char	acteristics (Note 2)	·				
V _{ON/OFF (th)}	Gate Threshold Voltage	$V_{IN} = V_{ON/OFF}, I_D = -250 \ \mu A$	0.4	0.9	1.5	V
R _{DS(on)}	Static Drain–Source On–Resistance (Q2)	$ \begin{array}{ll} V_{\rm IN} = 4.5 \ V, & I_{\rm D} = -0.8 \ A \\ V_{\rm IN} = 2.5 \ V, & I_{\rm D} = -0.7 \ A \\ V_{\rm IN} = 1.8 \ V, & I_{\rm D} = -0.6 \ A \end{array} $		155 193 248	260 330 450	mΩ
R _{DS(on)}	Static Drain–Source On–Resistance (Q1)	$ \begin{array}{ll} V_{IN} = 4.5 \; V, & I_D = 0.4 A \\ V_{IN} = 2.7 \; V, & I_D = 0.2 \; A \end{array} $		310 380	400 500	mΩ
Drain-Se	ource Diode Characteristics a	nd Maximum Ratings				
Is	Maximum Continuous Drain–Source				-0.25	Α
V _{SD}	Drain–Source Diode Forward	$V_{ON/OFF} = 0 V, I_S = -0.25 A(Note 2)$			-1.2	V

Notes: 1. R_{8JA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{8JC} is guaranteed by design while R_{8JA} is determined by the user's board design.

2. Pulse Test: Pulse Width < 300µs, Duty Cycle < 2.0%.

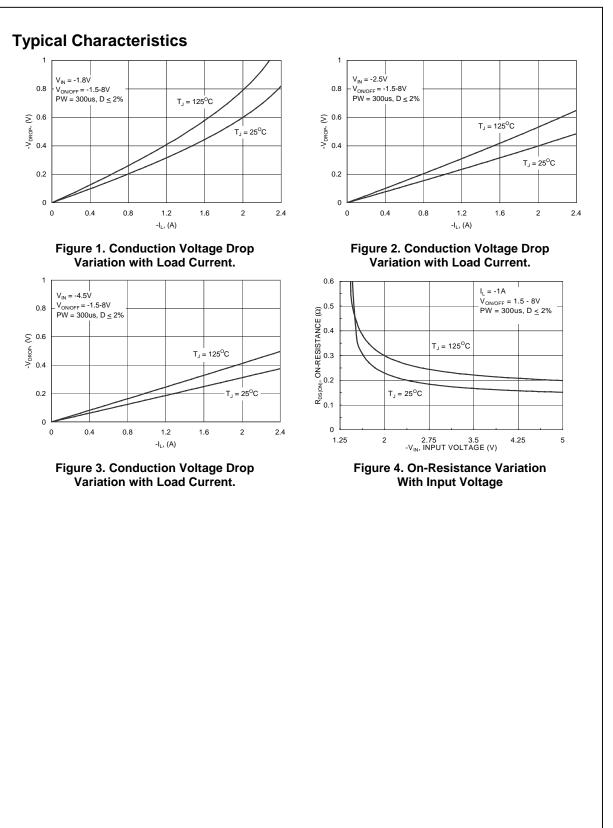
FDG6331L Load Switch Application Circuit



External Component Recommendation:

For additional in-rush current control, R2 and C1 can be added. For more information, see application note AN1030.

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EcoSPARK™	LittleFET™	Quiet Series [™]	UltraFET [®]
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Datasheet Identification	Product Status	Definition		
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